Product Change Notification

110804 - 01

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

Asia Pacific Contact: apacgccb@intel.com

Europe Email: eccb@intel.com

Japan Email: jccb.ijkk@intel.com

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Product Change Notification

Change Notification #:	**110804 - 01**
Change Title:	**Intel(R) Server System R1304BTLSHBN, Single, PCN 110804-01, Product Design, Product Material, Update Hot Swap Backplane, Reason for Revision: Update the TA number and the Projected Date**
Date of Publication:	**August 02, 2011**

Key Characteristics of the Change:

Product Design

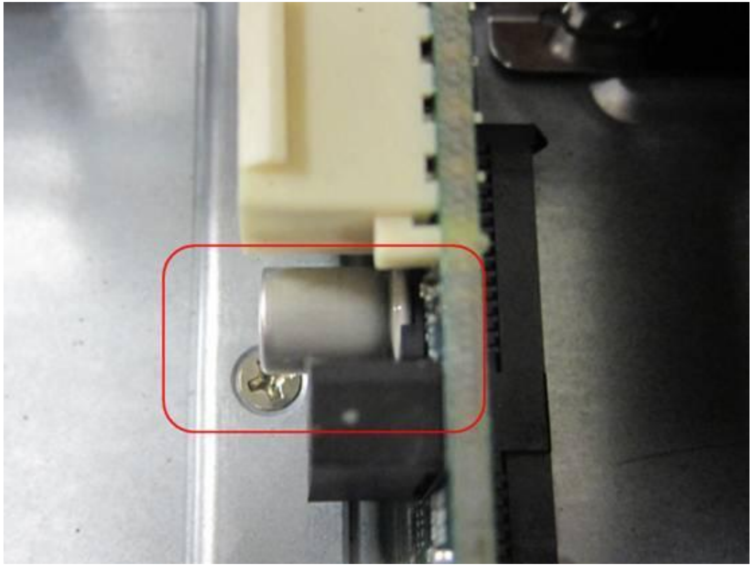
Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	Aug 19, 2011

Description of Change to the Customer:

Reason for Revision: Update the TA number and the Projected Date

Intel is updating the Hot Swap Backplane (HSBP) from Printed Board Assembly (PBA): G10396-204 to G10396-205 by changing the size of the capacitor to improve the HSBP assembly on the Intel® Server System R1304BTLSHBN. The height of the capacitor changed from 12.0mm to 7.7mm. The following is the picture of the old capacitor.



Customer Impact of Change and Recommended Action:

Intel recommends customers evaluate the changes and determine impacts to their specific applications when the updated products become available.

Products Affected / Intel Ordering Codes:

Pre Change Product Code	Pre Change MM#	Pre Change TA	Post Change Product Code	Post Change MM#	Post Change TA
R1304BTLSHBN	911688	G19777-002	R1304BTLSHBN	911688	G19777-003
R1304BTLSHBNNA	907658	G19777-002	R1304BTLSHBNNA	907658	G19777-003

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
June 28, 2011	00	Originally Published PCN
August 2, 2011	01	Update the TA number and the Projected Date